

# Wolfspeed Development of T-Gate Structure by Electron Beam Lithography

CNF Project Number: 3073-23

Principal Investigator(s): Evan Jones

User(s): Evan Jones, Jim Tajadod

Affiliation(s): Wolfspeed, Inc.

Primary Source(s) of Research Funding: Internal Research and Development

Contact: Evan.Jones@wolfspeed.com, Jim.Tajadod@wolfspeed.com

Primary CNF Tools Used: JEOL 9500

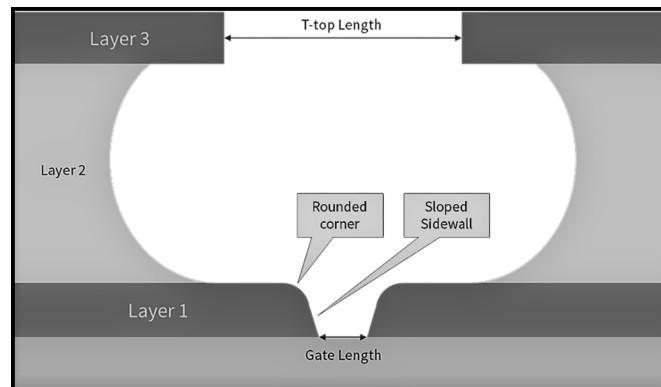


Figure 1: Schematic of target cross section.

## Abstract:

Wolfspeed aims to add electron-beam lithography (EBL) processes to our toolset to improve our competitive position in the RF electronics markets.

## Summary of Research:

Near term goals to be accomplished at Cornell NanoScale Facility (CNF) over a time range of 12 to 24 months include gain experience in EBL, identify baseline functional process for transfer into NC Fabrication upon toolset installation, and identify EBL toolset and facility specifications based on development work. Prototype demonstration of fully functional “T-Gate” HEMT 90 nm gate length with 30 nm overlay on 100 mm wafer processing. Long term goals to be accomplished beyond work at CNF include fully outfit EBL toolset, transfer process knowledge into NC Fab, and fully staff EBL process organization. A schematic of the target “T-Gate” profile is shown in Figure 1.

## Conclusions and Future Steps:

Work was initiated in the summer of 2023.

## References:

- [1] Chen, Y., et al. “T-Gate Fabrication Using a ZEP520A/UVIII Bilayer.” *Microelectronic Engineering*, vol. 57-58, 2001, pp. 939-943., [https://doi.org/10.1016/s0167-9317\(01\)00475-0](https://doi.org/10.1016/s0167-9317(01)00475-0).
- [2] Kim, Tae-Woo, et al. “Effect of a Two-Step Recess Process Using Atomic Layer Etching on the Performance of  $\text{In}_{0.52}\text{Al}_{0.48}\text{As}/\text{In}_{0.53}\text{Ga}_{0.47}\text{As}$  P-HEMTs.” *IEEE Electron Device Letters*, vol. 28, no. 12, 2007, pp. 1086-1088., <https://doi.org/10.1109/led.2007.910278>.
- [3] Ocola, Leonidas E., and Aaron Stein. “From Microchannels to Nanochannels in a Bilayer Resist.” *Nanofabrication: Technologies, Devices, and Applications*, 2005, <https://doi.org/10.1117/12.572068>.
- [4] Zhong, Yinghui, et al. “T.Gate Fabrication of Inp-Based HEMTs Using PMGI/ZEP520A/PMGI/ZEP520A Stacked Resist.” *Chinese Journal of Electronics*, vol. 25, no. 3, 2016, pp. 448-452., <https://doi.org/10.1049/cje.2016.05.009>.
- [5] Zhu, Mingsai, et al. “Nanofabrication of T Shape Gates for High Electron Mobility Transistors in Microwaves and THz Waves, a Review.” *Micro and Nano Engineering*, vol. 13, 2021, p. 100091., <https://doi.org/10.1016/j.mne.2021.100091>.
- [6] Fitch, Walker, et al. “Implementation of High-Power-Density X-Band AlGaIn/GaN High Electron Mobility Transistors in a Millimeter-Wave Monolithic Microwave Integrated Circuit Process” *IEEE Electron Device Letters*, Vol. 36, No. 10, October 2015.

